0603 [redacted] 贴片式发光二极管

特点（[redacted]）：

[redacted]

[redacted].6 [redacted]0.6 mm

[redacted] / [redacted]*0.8*0.6 mm

* [redacted] : /

Lumino[redacted]or and col[redacted]d: [redacted]een light/transparent colloid

* [redacted] ROHS

Environmental protection products Complied With ROHS Directive

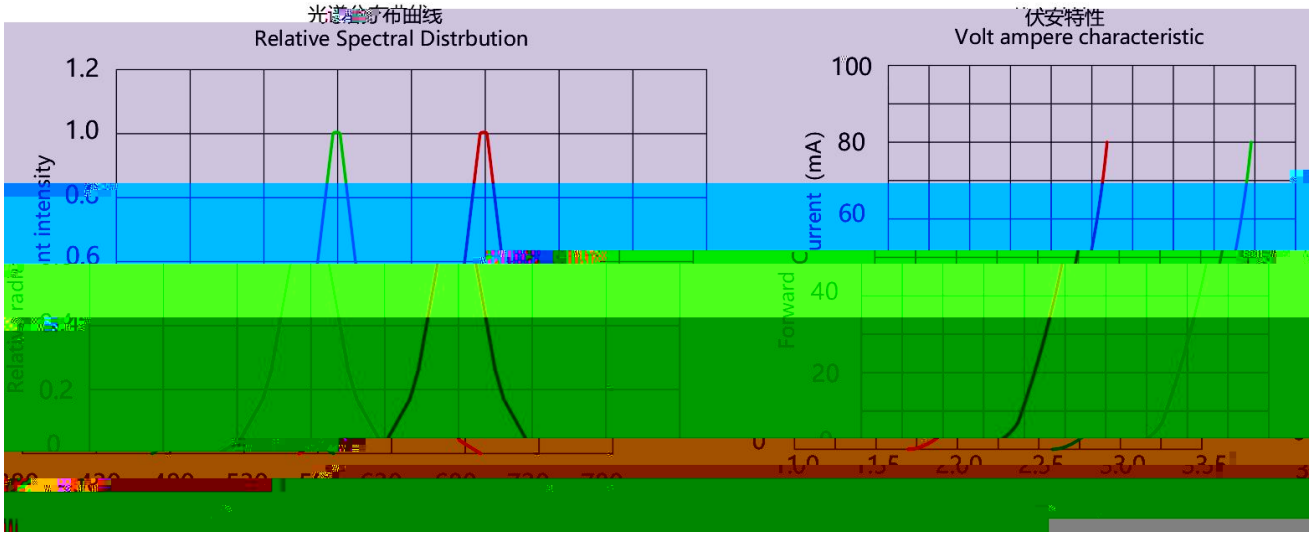
* [redacted] ee

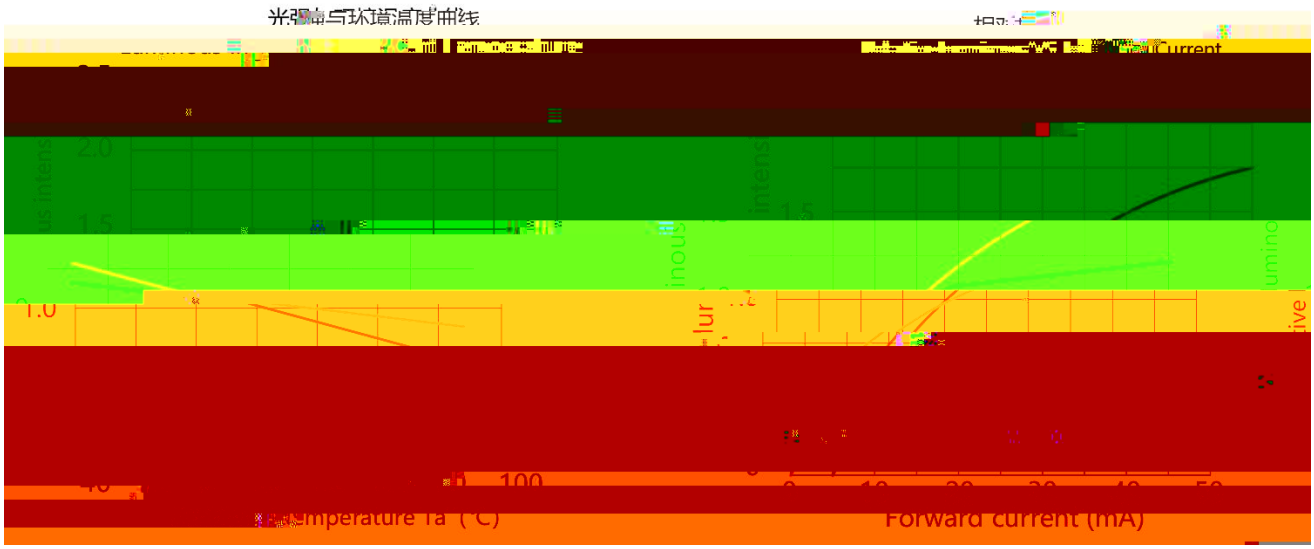
应用领域（P[redacted]）：

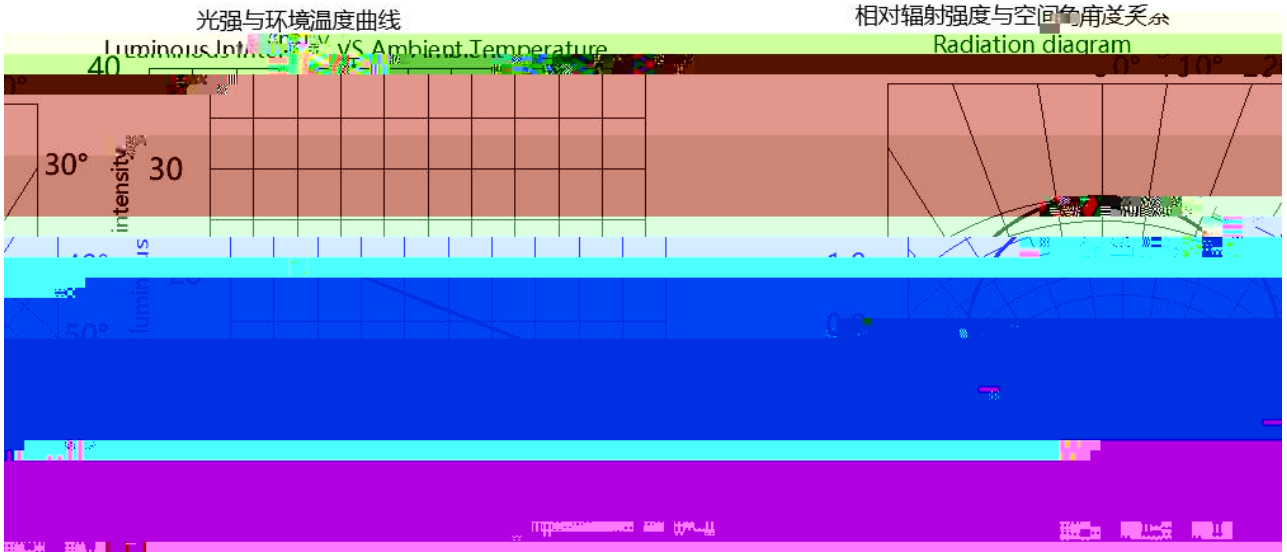
Part No. :X

典型特性曲线

Typical Characteristics Curves







25 ± 5 /Note If not otherwise indicated the test environment temp erature is 25 ± 5

Part No. :X

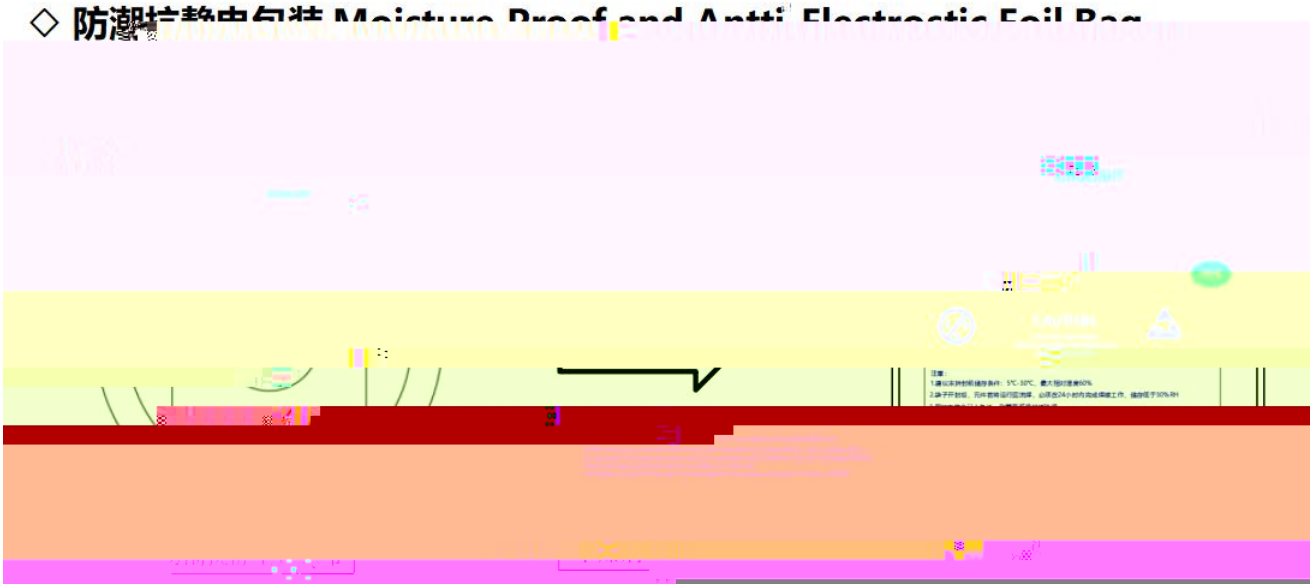
包装（1）

Packaging (1)

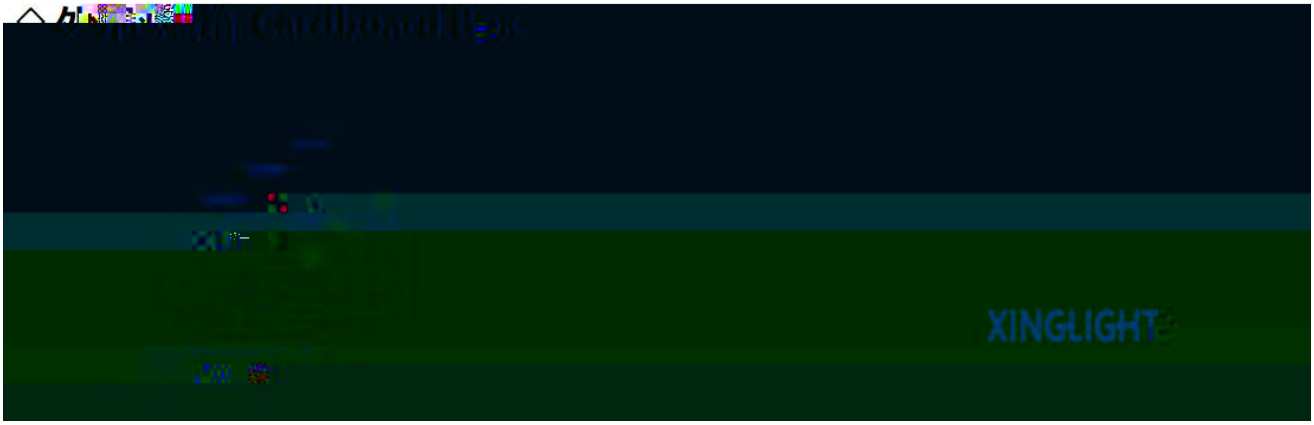
包装（2）

Packaging (2)

◇ 防潮抗静电包装 Moisture Proof and Antti Electrostic Foil Bag



◇ 外箱 Cardboard Box



◇ 标签说明 Label Expantion:

XINGLIGHT®

Part No. :X

焊接指导（2）

Guideline for Soldering (2)

清洗：

ضي U ضي 30 3 № 50

30

ٳ ٦ ╠ ۏ ٦ LED غ №

w 300W ٦ ↕ LED

ٲ ' ۏ ٦ LED

It is recommended that alcohol be used as a solvent for cleaning after soldering. Cleaning is to go under 30 for 3 minutes or 50 for 30 seconds. When using other solvents, it should be confirmed beforehand whether the solvents will dissolve the package and the resin or not.

Ultrasonic cleaning is also an effective way for cleaning. But the influence of Ultrasonic cleaning on LED depends on factors such as ultrasonic power. Generally, the ultrasonic power should not be higher than 300W. Before cleaning, a pretest should be done to confirm whether any damage to LEDs will occur.

*** 注意：** ٨ ↕ PCB غ ٲ ٳ ⌠ غ

ڏ PCB غ

* This general guideline may not apply to all PCB designs and configurations of all soldering equipment. The technics in practise is influenced by many factors, it should be specialized base on the PCB designs and configurations of the soldering equipment..

Part No. :X

XINGLIGHT®

Part

Precautions)

其他事项:

When handling the product, touching the encapsulant with bare hands will not but also affect on its optical characteristics. Excessive force to the encapsulant failure of the LEDs due to die breakage or wire deformation. For this reason, pl on LEDs, especially when the LEDs are heated such as during Reflow Soldering.

LED

The epoxy resin of encapsulant is